

Fig. 1

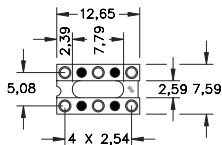


Fig. 2

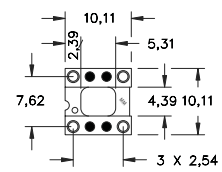


Fig. 3

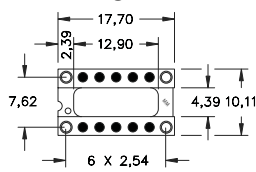
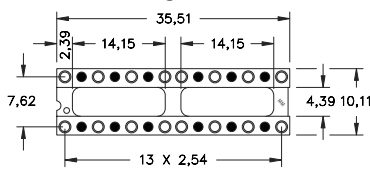
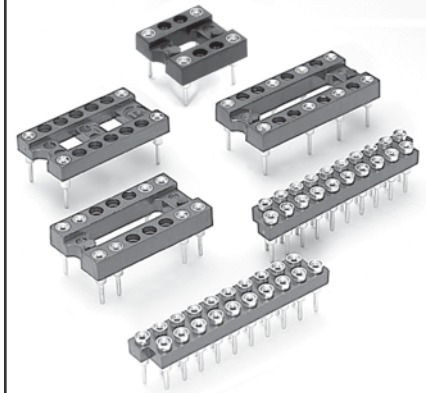


Fig. 4



○ = Loaded Position ● = Empty Position

- Relay sockets accept devices with I/O pins on 2,54 grid.
- Additional Relay DIP socket patterns are available on Page 86.1.
- Zig-Zag strip sockets are suitable for IC's and memory chips with staggered double row patterns.
- Series 110 and 410 use MM #1001 receptacles. See page 134 for details.
- Receptacles use Hi-Rel, 4 finger #30 BeCu contact rated at 3 amps. See page 208 for details.
- Insulators are high temp. thermoplastic.



Selectively Loaded Sockets For Dual-In-Line Relays

	No. of pins	Ordering Information
Fig. 1	6	110-XX-210-10-001000
Fig. 2	4	110-XX-308-10-001000
Fig. 3	4	110-XX-314-10-001000
Fig. 4	16	110-XX-328-10-001000

Staggered (Zig-Zag) Strip Sockets

Dim 'A'	No. of pins	Insulator Body	Ordering Information
18.97	14	Left, Stackable	410-93-214-10-001000
18.97	14	Right, Stackable	410-93-214-10-002000
21.51	16	Left, Stackable	410-93-216-10-001000
21.51	16	Right, Stackable	410-93-216-10-002000
26.59	20	Left, Stackable	410-93-220-10-001000
26.59	20	Right, Stackable	410-93-220-10-002000
31.67	24	Left, Stackable	410-93-224-10-001000
31.67	24	Right, Stackable	410-93-224-10-002000
36.75	28	Left, Stackable	410-93-228-10-001000
36.75	28	Right, Stackable	410-93-228-10-002000



XX= Plating Code
See Below

For RoHS compliance
select ◇ plating code.

SPECIFY PLATING CODE XX=	13◇	93	43◇
Sleeve (Pin)	0.25μm Au	5.08μm Sn/Pb	5.08μm Sn
Contact (Clip)	0.76μm Au	0.76μm Au	0.76μm Au